SDLS006

D2634, JANUARY 1981 REVISED MARCH 1988

- 8-Bit Serial-In, Parallel-Out Shift Registers with Storage
- Choice of 3-State ('LS595) or Open-Collector ('LS596) Parallel Outputs
- Shift Register Has Direct Clear
- Accurate Shift Frequency: DC to 20 MHz

description

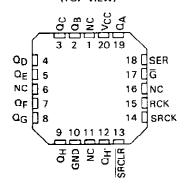
These devices each contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state ('LS595) or open-collector ('LS596) outputs. Separate clocks are provided for both the shift register and the storage register. The shift register has a direct-overriding clear, serial input, and serial output pins for cascading.

Both the shift register and storage register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the shift register state will always be one clock pulse ahead of the storage register.

SN54LS595, SN54LS596...J OR W PACKAGE SN74LS595, SN74LS596...N PACKAGE (TOP VIEW)

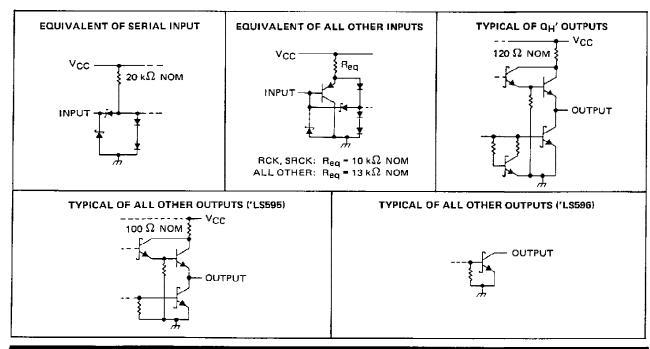
αв∏	1	U16]v _{cc}
oc□	2	15] Q _A
Qp∐	3	14	SER
QE 🗌	4	13]G
Q_{F}	5	12]RCK
ΩG□	6	11]SRCK
Он□	7	10	SRCLE
GND 🗌	8	9] ŒH.

SN54LS595, SN54LS596 . . . FK PACKAGE (TOP VIEW)



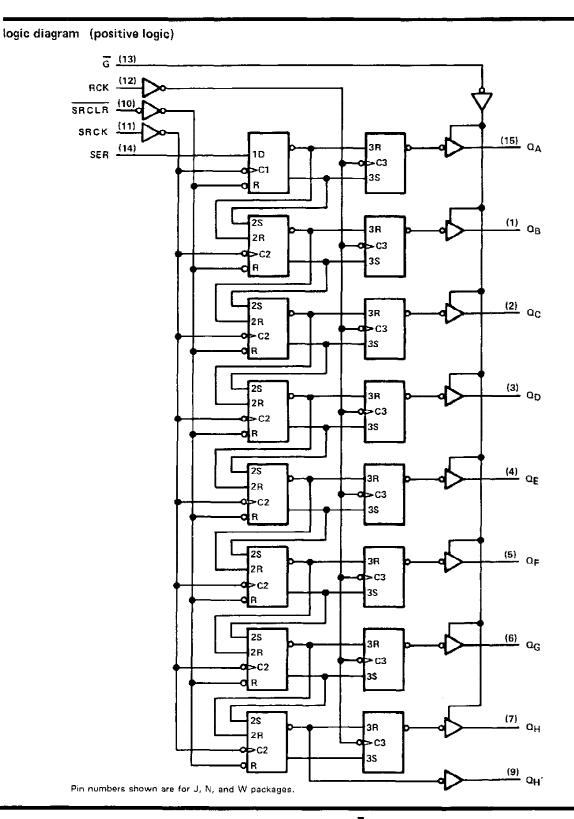
NC - No internal connection

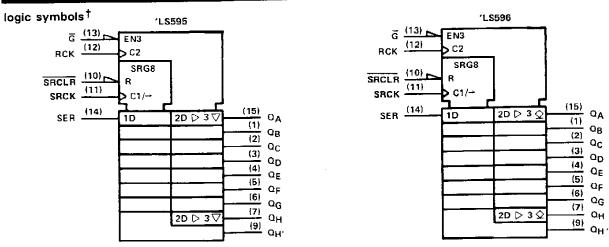
schematics of inputs and outputs



PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.







 $^{^{\}dagger}$ These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, Vcc (see Note 1)		
Input voltage		
Offictate output voltage		, , , , , , , , , , , , , , , , , , ,
Operation free-air temperature range:	SN54LS595, SN54LS596	, - 55°C to 125°C
	SN741 S595, SN74LS596	
Storage temperature range	.,,	

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

				SN54LS	3'	SN74LS'			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNI
V _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
VOH	High-level output voltage	QA thru QH, 'LS596 only			5.5			5.5	٧
		QH,			-1			- 1	mA
10H	High-level output current	Q _A thru Q _H , 'L\$595 only			- 1			- 2.6	
		OH'	8				16	mA	
†OL	Low-level output current	Q		_	12			24	
fSRCK	Shift clock frequency	1	0		20	0		20	МН
tw(SRCK)	Duration of shift clock pulse		25			25			ns
tw(RCK)	Duration of register clock pul	SE	20			20			ns
tw(SRCLR)	Duration of shift clear pulse,	low level	20			20			ns
77,0110 = 111		SRCLR inactive before SRCK 1	20			20]
		SER before SRCK † SRCK † before RCK † (see Note 2)				20			ns
t _{Sti}	Setup time					40			
		SRCLR low before RCK t	40			40			
th	Hold time	SER after SRCK †	0			0			ns
TA	Operating free-air temperatur	- 55		125	0		70	°C	

NOTE 2: This setup time ensures the register will see stable data from the shift-register outputs. The clocks may be connected together, in which case the storage register state will be one clock pulse behind the shift register.



SN54LS595, SN54LS596, SN74LS595, SN74LS596 8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS †			SN54LS'			SN74LS'		
FANA	UNICICA	TEST CONDITIONS			TYP#	MAX	MIN	TYP\$	MAX	UNIT
Vik		V _{CC} = MIN, I ₁ = - 18 mA				- 1.5			- 1.5	V
.,	'LS595 Q	V _{CC} = MIN, V _{IH} = 2 V,	10H = - 1 mA	2.4	3.2					
∨он		VIL = MAX	I _{OH} 2.6 mA				2.4	3.1		٧
lavi	^Q H′ ′LS596 Q	V _{CC} = MIN, V _{IH} = 2 V, V _I	1 _{OH} = -1 mA	2.4	3.2	0.1	2.4	3.2	0.1	mA
ТОН	F2236 (1	ACC = MIM' AIH = 5 A' AI		<u> </u>			 	0.25	0.1	mA
	a	V _{CC} = MIN, V _{IH} = 2 V,	IOL = 12 mA		0.25	0.4	-	0.25	0.4	
Vol		VII = MAX	101 = 8 mA		0.25	0.4		0.25	0.4	V
	QH'	TIE MAN	I _{OL} = 16 mA					0.35	0,5	
^I OZH	'LS595 Q	VCC = MAX, VIH = 2 V, VI	L = MAX, V _{OH} = 2.7 V			20			20	μA
IOZL	'LS595 Q	V _{CC} = MAX, V _{IH} = 2 V, V _{II}	L = MAX, V _{OH} = 0.4 V			- 20			- 20	μА
li .		VCC = MAX, VI = 7 V				0.1			0.1	mA
ЧН		V _{CC} - MAX, V ₁ - 2.7 V				20			20	μΑ
IJЦ	SER	Vcc = MAX, V1 = 0.4 V		- 0.4				- 0.4	mΑ	
' '1 <u> </u> 	All others	· (C 141/14)				- 0.2	<u> </u>		- 0.2	
OS §	'LS595 Q	V _{CC} = MAX, V _O = 0 V		- 30		130	- 30		– 130	mΑ
.05	ΩH,		– 20		- 100	- 20		– 100		
¹ ссн	'LS595			33		50		33	50	mΑ
CCII	'LS596	$V_{CC} = MAX$			30	45		30	45	
ICCL	'LS595	All possible inputs grounded,			42	65		42	65	mA
	'LS596	All outputs open			36	55		36	55	
¹ccz	'L S 595				44	65		44	65	mA.

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

SN54LS595, SN54LS596, SN74LS595, SN74LS596 8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES

switching characteristics, VCC = 5 V, TA = 25° C (see note 3)

DADAMETER	FROM	то	7557.004	'LS595			'LS596			UNIT	
PARAMETER	(INPUT) (OUTPUT		TEST CON	MIN TYP		MAX	MIN	TYP	MAX	UNII	
tPLH .	SRCK1		5 0 5			12	18		14	21	ns
^t PHL	SHUK	QH'	R _L = 1kΩ,	C _L = 30 pF		17	25		20	30	ns
t _{PLH}	RCK 1	Q _A thru Q _H	R _L = 667 Ω,	C _L = 45 pF	1	12	18		28	42	ns
^t PHL	nck '	da iiiu da				24	35		24	35	ns
tPZH	<u>G</u> †	Q _Δ thru Q _H				20	30				ns
tPZL	1 " "	GA IIII GH				25	38		_		ns
tPHZ	G t	Q _A thru Q _H	$R_1 = 667 \Omega_s$	C _L = 5 pF		20	30_				ns
tPLZ	1 3 '	QA BII U QH	11 - 00, 32,			25	38				ns
tPLH	G†	Qд thru QН	$R_1 = 667 \Omega_s$	C ₁ = 45 pF			·		40	60	ns
^t PHL	Ğ+	Q _A thru Q _H	11 - 007 12,	CL - 40 hr					25	38	ns
^t PHL	SRCLR +	QH'	$R_L = 1 k\Omega$,	CL = 30 pF		24	35		24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-86717012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8671701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8671701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8671701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8671701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS595N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS595N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS595NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS595NSRE4	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS596D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS596D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS596N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS596N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type



PACKAGE OPTION ADDENDUM

24-Oct-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS596NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS596NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS595FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS595FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS595J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS595W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS595W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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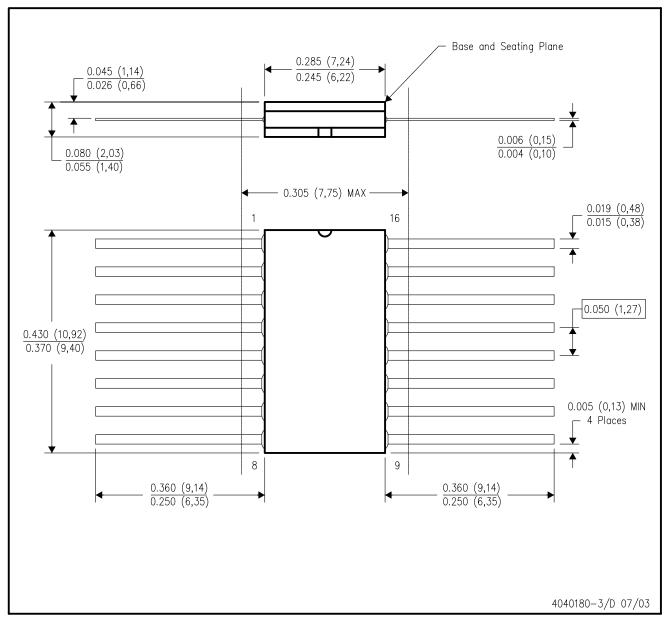
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



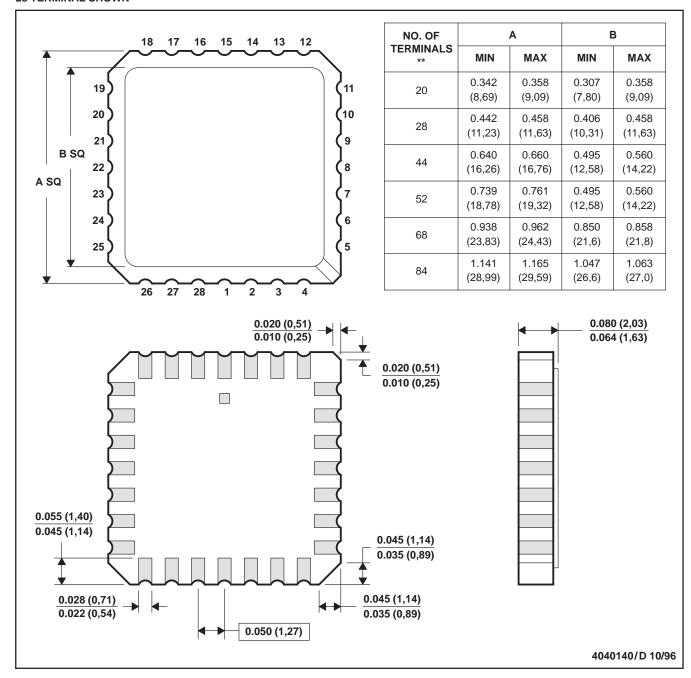
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

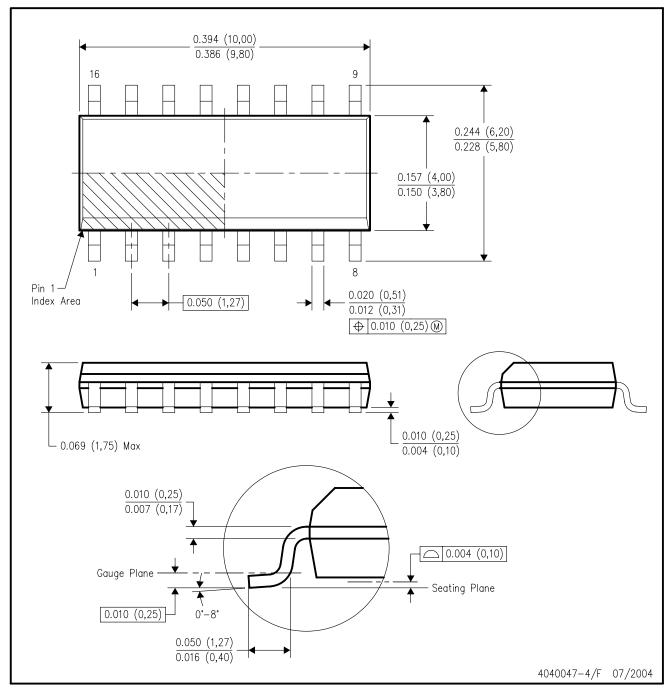


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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Post Office Box 655303 Dallas, Texas 75265

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